

## Taiwan Semiconductor

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	50	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	1.5	°C/W

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode <sup>(1)</sup>	I <sub>F</sub> = 15A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	0.70	V
	I <sub>F</sub> = 30A, T <sub>J</sub> = 25°C		-	0.90	V
	I <sub>F</sub> = 15A, T <sub>J</sub> = 125°C		-	0.60	V
	I <sub>F</sub> = 30A, T <sub>J</sub> = 125°C		-	0.75	V
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>	T <sub>J</sub> = 25°C	· I <sub>R</sub>	-	200	μΑ
	T <sub>J</sub> = 125°C		-	15	mA

#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
MBRS30H45CT	TO-263AB (D <sup>2</sup> PAK)	800 / Tape & Reel	



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

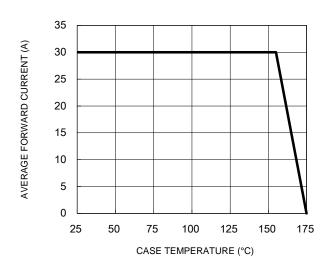


Fig.2 Typical Junction Capacitance

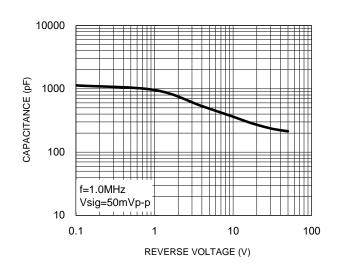
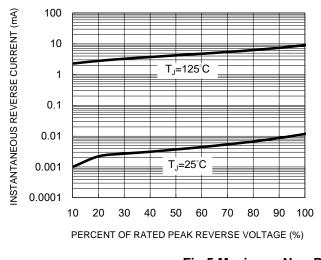


Fig.3 Typical Reverse Characteristics

Fig.4 Typical Forward Characteristics



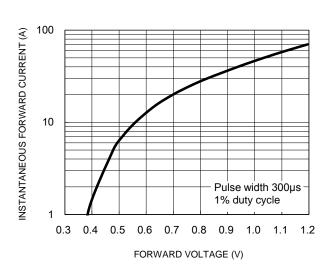
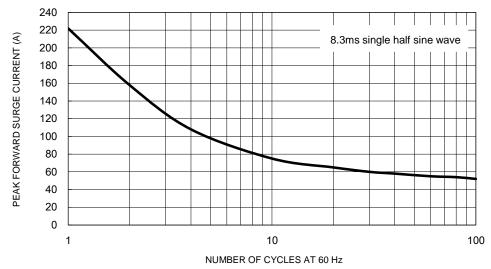


Fig.5 Maximum Non-Repetitive Forward Surge Current



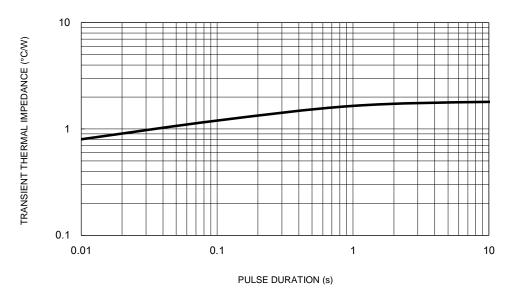
3



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

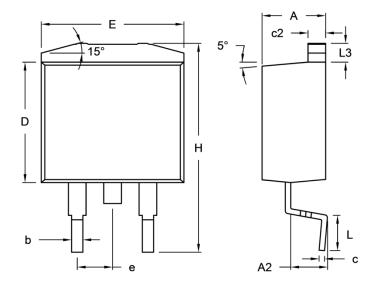
Fig.6 Typical Transient Thermal Impedance





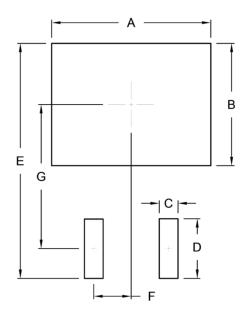
## **PACKAGE OUTLINE DIMENSIONS**

## TO-263AB (D<sup>2</sup>PAK)



DIM.	Unit (mm)		Unit (	(inch)
DIM.	Min.	Max.	Min.	Max.
Α	4.44	4.70	0.175	0.185
A2	2.03	2.79	0.080	0.110
b	0.68	0.94	0.027	0.037
С	0.36	0.53	0.014	0.021
c2	1.14	1.40	0.045	0.055
D	8.25	9.25	0.325	0.364
E	-	10.50	-	0.413
е	2.41	2.67	0.095	0.105
Н	14.60	15.88	0.575	0.625
L	2.29	2.79	0.090	0.110
L3	1.14	1.40	0.045	0.055

#### **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	10.80	0.425
В	8.30	0.327
С	1.27	0.050
D	4.05	0.159
E	15.95	0.628
F	2.54	0.100
G	9.775	0.385

#### **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

YWW = Date Code F = Factory Code



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